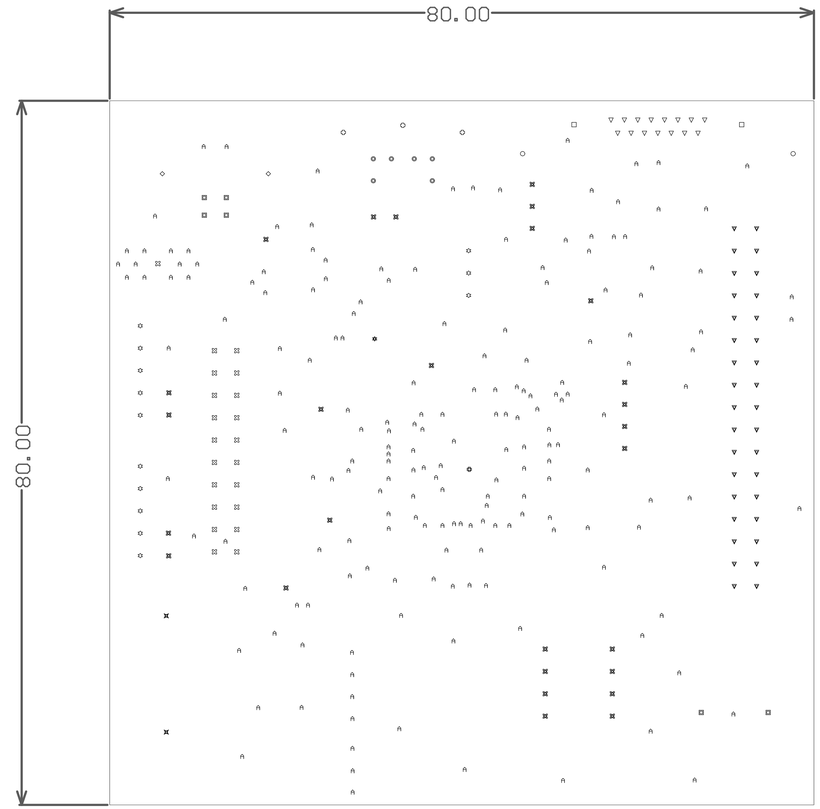

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer	Copper	1.40mil		
	Dielectric 1	FR-4	12.60mil	4.8	
2	Mid Layer 1	Copper	1.40mil		
	Dielectric 3	FR-4	31.39mil	4.8	
3	Mid Layer 2	Copper	1.40mil		
	Dielectric 2	FR-4	12.60mil	4.8	
4	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
	1	1.300mm (51.18mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v165h130			
	1	3.700mm (145.67mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c400h370			
	2	1.850mm (72.84mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c280h185m0p100280			
	2	1.930mm (75.98mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c96hn193			
	2	1.930mm (75.98mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c290h193			
	2	2.300mm (90.55mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c380h230			
	3	2.290mm (90.16mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c349h229m349p100349			
	6	0.890mm (35.04mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
	6	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
	13	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
	15	0.700mm (27.56mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
	21	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
	27	0.800mm (31.50mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
	34	1.200mm (47.24mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
	188	0.250mm (9.84mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)			
	323 Total										

AVED

ENGINEER: DAR

PCB DESIGNER: DAR

TITLE: MB2K2 V1A

DATE: 4/27/2020

PART NO.:

REV: V1

FILE NAME: MB2K2_V1.PcbDoc

DWG NO:

SCALE: